

IN THE CLAIMS

1. (Currently amended) A method comprising:
temporarily flattening a sheet;
processing said sheet applying row and column electrodes to said sheet while said sheet is held in a flattened configuration; and
securing said sheet to a second sheet while continuing to hold said sheet in a flattened configuration.
2. (Original) The method of claim 1 wherein temporarily flattening the sheet includes placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.
3. Canceled.
4. (Currently amended) The method of claim [[3]] 1 wherein processing said sheet includes applying a light emitting material to said sheet.
5. (Original) The method of claim 4 wherein applying a light emitting material to said sheet includes applying an organic light emitting material between said row and column electrodes.
6. (Original) The method of claim 1 further including processing said second sheet in a flattened configuration.
7. (Original) The method of claim 6 including processing said second sheet in a chuck.
8. (Original) The method of claim 7 including processing both said first and second sheets in chucks and combining said sheets using said chucks.
9. (Original) The method of claim 1 including securing said first and second sheets to an integrator plate.

10. (Original) The method of claim 9 including surface mounting said first and second sheets.

11. (Original) The method of claim 8 including surface mounting said first and second sheets in said chucks.

12. (Currently amended) A method comprising:
receiving a warped sheet;
temporarily flattening said sheet for processing;
processing said flattened, warped sheet by applying electrodes to said sheet; and
securing said flattened, warped sheet to a planar surface.

13. (Original) The method of claim 12 including securing said flattened sheet to a second sheet while continuing to hold said flattened sheet in a flattened configuration.

14. (Original) The method of claim 12 wherein temporarily flattening the sheet includes placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.

15. (Original) The method of claim 12 including securing said flattened sheet to a rigid, planar integrating plate.

16. (Currently amended) A method comprising:
temporarily flattening a ceramic sheet;
processing a glass panel to define row and column electrodes thereon while continuing to hold said sheet in a flattened configuration; and
securing said sheet to said glass panel while continuing to hold said sheet in a flattened configuration.

17. (Original) The method of claim 16 including securing said sheet and said panel to an integrating plate.

18. (Original) The method of claim 16 wherein temporarily flattening the ceramic sheet by placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.

19. (Original) The method of claim 16 wherein processing said panel further includes applying an organic light emitting material between said row and column electrodes.

20. (Original) The method of claim 16 further including processing both said sheet and said panel in chucks and combining said sheet and said panel using said chucks.